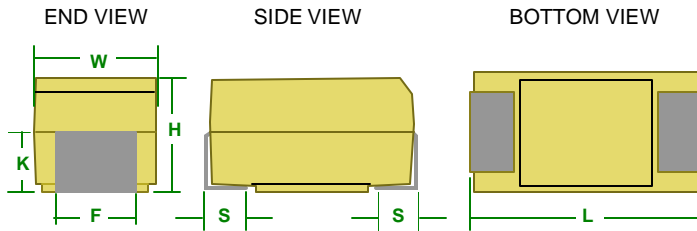


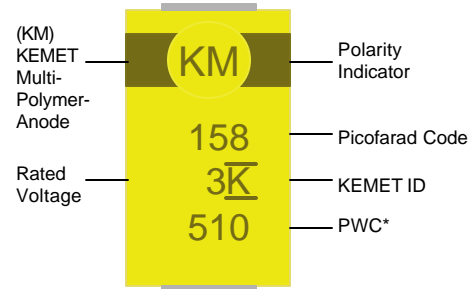
T530 Series - KEMET Multi-Polymer-Anode Tantalum Chip Capacitor

New Product Specification 2/24/06

Component Outline Drawing



Component Marking



* 510 = 10th week of 2005

| Case Codes | | Component Dimensions | | | | | |
|------------|---------|----------------------|---------|---------|----------|------------|------------|
| | | L | W | H | K Min | F ± 0.1 | S ± 0.2 |
| KEMET | EIA | | | | | | |
| D | 7343-31 | 7.3±0.3 | 4.3±0.3 | 2.8±0.3 | 1.3 | 2.4 | 1.3 |
| Y | 7343-40 | 7.3±0.3 | 4.3±0.3 | 4.0 max | 1.9 | 2.4 | 1.3 |
| X | 7343-43 | 7.3±0.3 | 4.3±0.3 | 4.0±0.3 | 2.1 | 2.4 | 1.3 |

Part Number and Electrical Specification Table

| KEMET Part Number | Case | Cap | Voltage | DCL V _R | DF 120Hz | ESR, 100kHz | Ripple Current (Arms) @ 100 kHz | |
|----------------------|-----------|--------|---------|-----------------------|-------------|----------------|-------------------------------------|---------------------------|
| | | | | | | | delta T=20°C @ -55°C to 105°C | delta T=2°C @ 125°C |
| T530X687M004A(*)E004 | X/7343-43 | 680 µF | 4 V | 272 µA | 8 % | 4 mΩ | 8.2 | 2.6 |

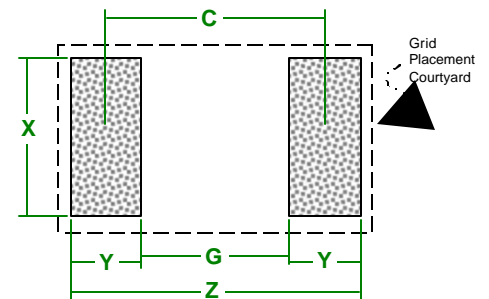
(*) Insert "T" for 100% tin (Sn) termination or "H" for tin/lead (Sn/Pb)

Land Pattern Dimensions for Reflow Solder

| KEMET/EIA Size Code | Pad Dimensions | | | | | |
|---------------------|----------------|------|------|------------|------------|--|
| | Z | G | X | Y (ref) | C (ref) | |
| D/7343-31 | 8.90 | 3.80 | 2.70 | 2.55 | 6.35 | |
| Y/7343-40 | 8.90 | 3.80 | 2.70 | 2.55 | 6.35 | |
| X/7343-43 | 8.90 | 3.80 | 2.70 | 2.55 | 6.35 | |

Packaging Specifications

| KEMET | EIA | | Part | Sprocket | 180mm (7" dia) | 330mm (13" dia) |
|-------|---------|--------|------|----------|-------------------|--------------------|
| D | 7343-31 | 12±0.3 | 8 | 4 | 500 | 2500 |
| Y | 7343-40 | 12±0.3 | 8 | 4 | 500 | 2000 |
| X | 7343-43 | 12±0.3 | 8 | 4 | 500 | 2000 |



2/24/06